



General Description

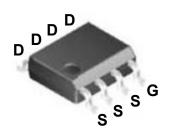
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

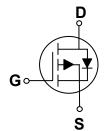
BV _{DSS}	R _{DS(ON)}	Ι _D
-40 V	35 mΩ	-6 A

Features

- $R_{DS(ON)} \leq 35 m\Omega @V_{GS} = -10V$
- Fast Switching
- · Green Device Available
- Suit for -4.5V Gate Drive Applications

SOP-8 Pin Configuration





Applications

- · Load Switch
- · Synchronous Rectification

	bsolute Maximum Ratings T _J =25°C unless otherwise noted							
Symbol	Parameter	Rating	Units					
V_{DS}	Drain-Source Voltage	-40	V					
V_{GS}	Gate-Source Voltage	±20	V					
I _D	Drain Current - Continuous (T _C =25°C)	-6	Α					
I _{DM}	Drain Current - Pulsed (T _C =25°C) (NOTE 1)	-24	Α					
P_D	Power Dissipation (T _C =25°C)	3.8	W					
T_J	Operating Junction Temperature Range	-55 to 150	°C					
T _{STG}	Storage Temperature Range	-55 to 150	°C					
Marking Code		PD035						

Thermal Characteristics					
Symbol	Parameter		Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		85.7	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case		32.9	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V , I_D = -250uA	-40			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} = -32V , V_{GS} = 0V			-1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = ±20V , V_{DS} = 0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V_{GS} = -10V , I_D = -3A			35	mΩ
		V_{GS} = -4.5V , I_D = -2A			60	11122
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = -250 uA$	-1.0		-2.5	V

Dynamic and switching Characteristics (NOTE 3)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V = 20V V = 40V		26.9		
Q_{gs}	Gate-Source Charge	V_{DS} = -20V , V_{GS} = -10V ,		4.88		nC
Q_{gd}	Gate-Drain Charge	- ib		4.51		
$T_{d(on)}$	Turn-On Delay Time	V_{DS} = -30V , V_{GS} = -10V , R_{GEN} =6 Ω , I_{D} = -1A		4.8		
T _r	Rise Time			17.6		nS
$T_{d(off)}$	Turn-Off Delay Time			88.5		110
T _f	Fall Time			48.8		
C _{iss}	Input Capacitance	V _{DS} = -20V , V _{GS} = 0V , F= 1MHz		1316		
C _{oss}	Output Capacitance			102		pF
C _{rss}	Reverse Transfer Capacitance			78		
R_g	Gate Resistance	V_{DS} = 0V , V_{GS} = 0V , F= 1MHz		11		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V_{SD}	Diode Forward Voltage	V_{GS} = 0V , I_{S} = -1A			-1.1	V

NOTES:

- 1. Max. current is limited by bonding wire.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- ${\it 3. Guaranteed by design, not subject to production testing.}\\$





Characteristics Curves

FIG. 1-On-Resistance vs I_D

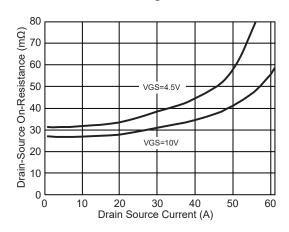


FIG. 2-Gate Threshold Voltage

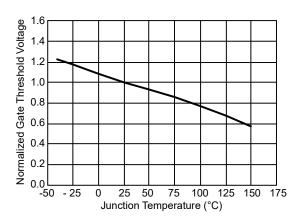


FIG. 3-Source-Drain Diode Forward

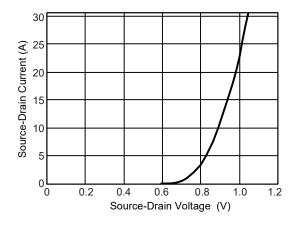


FIG. 4-Gate Charge Characteristics

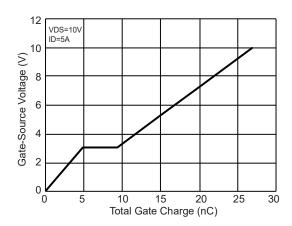


FIG. 5-Drain Current

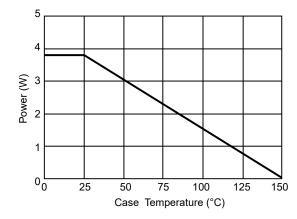
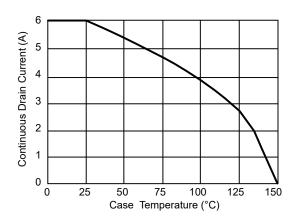


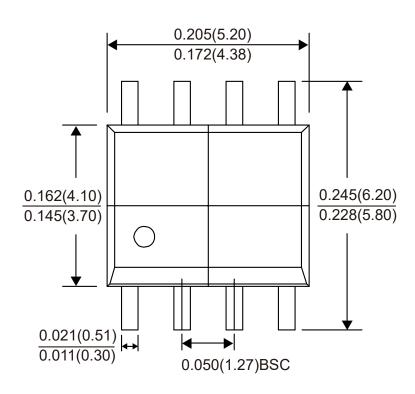
FIG. 6-Power Dissipation

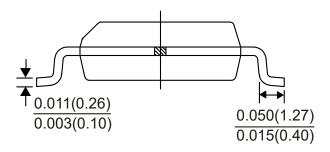


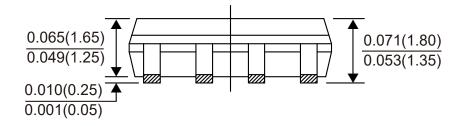




Package Outline Dimensions







SOP-8Dimensions in inches and (millimeters)





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